

LNPTM STAT-KONTM COMPOUND DX09315C

DESCRIPTION

LNP STAT-KON DX09315C compound is based on Polycarbonate (PC) resin containing 15% carbon fiber. Added features of this grade include: LNP Clean Compounding Technology, Low LPC, Low Ionics, Low Outgassing, Low C18-C40 Hydrocarbons, Electrically Conductive.

GENERAL INFORMATION	
Features	Electrically Conductive, Good Processability, Low ionics/Outgassing/Liquid particle count, Carbon fiber filled, High stiffness/Strength, No PFAS intentionally added
Fillers	Carbon Fiber
Polymer Types	Polycarbonate (PC)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Electronic Components
Industrial	Material Handling

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, brk, Type I, 5 mm/min	123	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	3	%	ASTM D638
Tensile Modulus, 5 mm/min	9810	MPa	ASTM D638
Flexural Stress	201	MPa	ASTM D790
Flexural Modulus	8130	MPa	ASTM D790
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	732	J/m	ASTM D4812
Izod Impact, notched, 23°C	94	J/m	ASTM D256
THERMAL ⁽¹⁾			
HDT, 1.82 MPa, 3.2mm, unannealed	125	°C	ASTM D648
CTE, -40°C to 40°C, flow	1.3E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	7.E-05	1/°C	ASTM E831
Relative Temp Index, Elec ⁽²⁾	80	°C	UL 746B
Relative Temp Index, Mech w/impact ⁽²⁾	80	°C	UL 746B
Relative Temp Index, Mech w/o impact ⁽²⁾	80	°C	UL 746B
PHYSICAL ⁽¹⁾			
Specific Gravity	1.25		ASTM D792
Mold Shrinkage, flow, 3.2 mm ⁽³⁾	0.1 – 0.2	%	SABIC method
Mold Shrinkage, xflow, 3.2 mm ⁽³⁾	0.3 – 0.4	%	SABIC method
Melt Volume Rate, MVR at 300°C/2.16 kg	26	cm³/10 min	ISO 1133
ELECTRICAL ⁽¹⁾			
Surface Resistivity	1.E+04 – 5.E+05	Ω	ASTM D257

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CHEMISTRY THAT MATTERS



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
FLAME CHARACTERISTICS (2)			
UL Yellow Card Link	E207780-101901972	-	-
UL Recognized, 94HB Flame Class Rating	≥1	mm	UL 94
INJECTION MOLDING ⁽⁴⁾			
Drying Temperature	90 – 110	°C	
Drying Time	3 – 5	Hrs	
Melt Temperature	280 – 320	°C	
Nozzle Temperature	280 – 320	°C	
Front - Zone 3 Temperature	280 – 320	°C	
Middle - Zone 2 Temperature	280 – 320	°C	
Rear - Zone 1 Temperature	250 – 280	°C	
Mold Temperature	90 – 120	°C	
Back Pressure	1 – 5	MPa	
Screw Speed	30 – 100	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.

(3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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